

Smart Card

TE Internal #: 5145299-2

Connector, 8 Position, 2.54 mm [.1 in] Centerline, Board Mount, -40

– 90 °C [-40 – 194 °F], Smart Card Connectors

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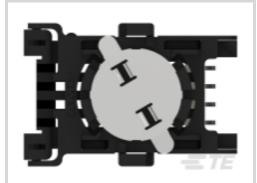
Connectors > PCB Connectors > Memory Card Connectors > Smart Card Connectors











Smart Card Connector Product Type: Connector

Number of Positions: 8

Pre-Installed Wire & Cable: Without
Centerline (Pitch): 2.54 mm [.1 in]
Contact Current Rating (Max): .2 A

Features

Product Type Features

Compatible Card	SIM/SAM
Connector & Contact Terminates To	Printed Circuit Board
Smart Card Connector Product Type	Connector
Configuration Features	
Cover	With
	\ A /: .

Cover	With
Card Detection Switch	With
Operating Function	NO
Number of Signal Positions	6
Number of Positions	8
Pre-Installed Wire & Cable	Without

Body Features

Primary Product Color	Black	
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Contact Features

Contact Mating Area Plating Material	Gold	
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Contact Underplating Material	Nickel
PCB Contact Termination Area Plating Material	Tin
Contact Base Material	Phosphor Bronze
Contact Current Rating (Max)	.2 A
Termination Features	
Termination Method to PCB	Surface Mount

Mechanical Attachment

Mating Alignment	With
Connector Mounting Type	Board Mount

Housing Features

Housing Material	High Temperature Thermoplastic
Centerline (Pitch)	2.54 mm[.1 in]

Dimensions

Accepts Card Thickness	.76 mm[.03 in]
Profile Height from PCB	1.55 mm, 4.05 mm[.059 in][.159 in]

Usage Conditions

Operating Temperature Range	-40 - 90 °C[-40 - 194 °F]

Operation/Application

Durability Rating	10000 Cycles
Circuit Application	Signal

Packaging Features

Packaging Quantity	500
Packaging Method	Carton

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2024 (241)



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Does	not	contain	KEACH	SVHU

Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per
	homogenous material. Also BFR/CFR/PVC
	Free

Solder Process Capability

Reflow solder capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts







Customers Also Bought













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Documents

Product Drawings

SIM/SAM RECPT,6 POS,SMT

English

CAD Files

Customer View Model

ENG_CVM_CVM_5145299-2_O.2d_dxf.zip

English

3D PDF

3D

Customer View Model

ENG_CVM_CVM_5145299-2_O.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_5145299-2_O.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Product Specifications

Application Specification

English

Application Specification

English